CLAIMS

[1] A thermally conductive composition comprising:

a base polymer, an adhesive polymer, and thermally conductive particles,

wherein a thermal conductivity of the thermally conductive composition is 0.3 W/m·K or more,

the thermally conductive particles include inorganic particles (a) with a specific surface area of 1 m^2/g or less,

the inorganic particles (a) are coated with the adhesive polymer, and

the adhesive polymer contains a methyl hydrogen polysiloxane, an epoxy group-containing alkyltrialkoxysilane, and a cyclic polysiloxane oligomer.

[2] The thermally conductive composition according to claim 1, wherein the base polymer is a silicone polymer.

[3] The thermally conducive composition according to claim 1 or 2, wherein a tensile lap-shear strength of the adhesive polymer with respect to an aluminum plate is 50 N/cm^2 or more.

[4] The thermally conductive composition according to any one of claims 1 to 3, wherein the base polymer is an addition curable silicone polymer.

[5] The thermally conductive composition according to any one of claims 1 to 4, further comprising a silicone oil.

[6] The thermally conductive composition according to any one of claims 1 to 5, wherein the thermally conductive particles are composed of at least one selected from a metal oxide, a metal hydroxide, a metal nitride, and silica.

[7] The thermally conductive composition according to any one of claims 1 to 6, further comprising inorganic particles (b) with a specific surface area of more than 1 m^2/g.

[8] The thermally conductive composition according to claim 7, wherein the inorganic particles (b) are surface treated with a silane compound, a titanate compound, an aluminate compound, or partial hydrolysates thereof.

[9] The thermally conductive composition according to any one of claims 1 to 8, wherein the thermally conductive composition is in the form of a sheet.

[10] The thermally conductive composition according to any one of claims 1 to 9, wherein an amount of the adhesive polymer is 5 to 35 parts by weight with respect to 100 parts by weight of the base polymer.

[11] A method for producing the thermally conductive composition according to any one of claims 1 to 10, comprising:

a first mixing process of mixing the adhesive polymer and the inorganic particles (a) with a specific surface area of 1 m^2/g or less so that the inorganic particles (a) are coated with the adhesive polymer;

a second mixing process of adding and mixing the base polymer; and

a curing process.

[12] The method according to claim 11, wherein the inorganic particles (b) with a specific surface area of more than 1 m^2/g are added in the second mixing process.